

SPECIFICATION



SMD DR Bandpass Filter

DR / Ceramic / LC / Waveguide / Microstrip / Helical

Date: 2024.06.18

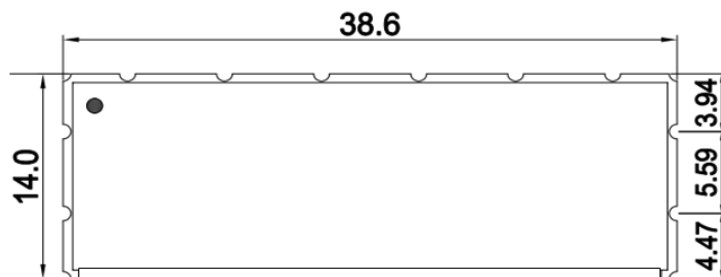
Written by	Checked by	Approval
FL Lai	MY Chen	CK Chang

ELECTRICAL SPECIFICATIONS

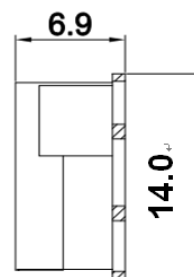
ITEM	SPEC	UNIT
1	Center Frequency [fo]	1460.0
2	Bandwidth [BW]	[1442.0~14780.0]
3	Insertion Loss	2.5 max (in regular temp)
4	Pass Band Ripple	0.5 max (in regular temp)
5	VSWR	1.5 max (in regular temp)
6	Attenuation	70.0 min. @ [DC ~ 1200.0] MHz (in regular temp)
		50.0 min. @ [1390 ~ /] MHz (in regular temp)
		45.0 min. @ [1530.0 ~ /] MHz (in regular temp)
		70.0 min. @ [1700.0 ~ 3000.0] MHz (in regular temp)
7	Power	1.0
8	In/Out Impedance	50.0
9	Group Delay	12.0
10	Operation Temperature Range	-20°C to +85°C
11	Storage Temperature Range	-50°C to +90°C

MECHANICAL SPECIFICATIONS

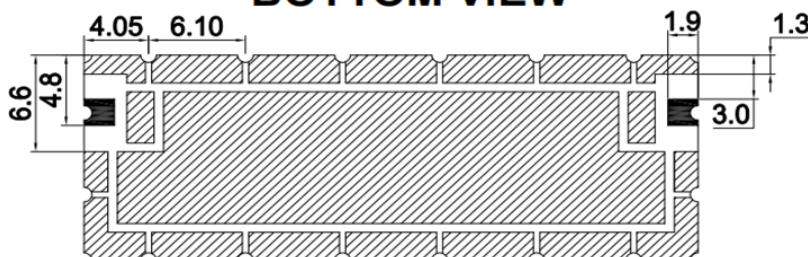
TOP VIEW



RIGHT VIEW



BOTTOM VIEW

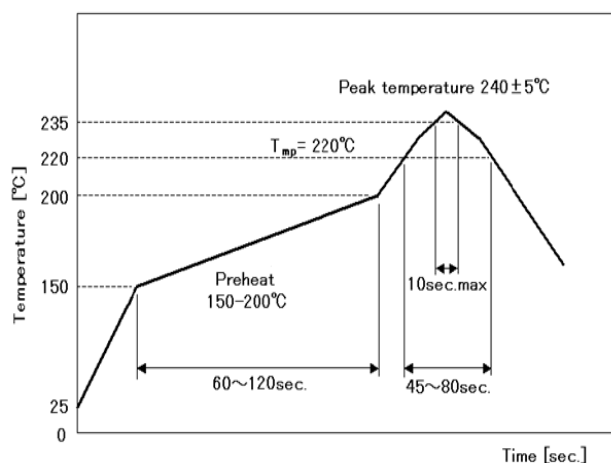


 I/O PORT
 GROUND
 TOLERANCE : ±0.30
 Unit : mm
 XXXXXXXXXX: 批次号
 YYY: 序列号
 ● : 输入

PERFORMANCE



SOLDERING CONDITION



Remark:

1. Please ensure that the good grounding (ground and I/O part area). When the product is used, in order to ensure good grounding ,bottom area after soldering, that need for the side pin to repair welding.
2. Product recommended using SMT process, the above is recommended reflow temperature curve. Because of different substrate and reflow soldering equipment varies , according to the substrate and reflow soldering equipment to confirm the actual temperature curve.
3. If special occasion occurs which needs manual soldering, the temperature should be 350°C ,but not Over 3 times, and reflow and manual soldering should not be over 3 times.
4. The internal solder has a melting point of 217°C . It is recommended to use solder paste with a melting point of 183°C for SMT.